

IN THE CLAIMS:

A listing of the claims as now amended, including additions in underline and deletions in strikethrough, is provided below.

1. (Canceled)

2. (Currently Amended) ~~A~~ The resin sealing mold assembly according to Claim 1, having an upper mold and a lower mold, comprising:

a substantially hexahedral cavity for housing at least a lead frame and a semiconductor element; and

at least one air releasing groove formed at contact surface of at least the upper mold or the lower mold positioned at at least one corner of the hexahedral cavity;

wherein a distance between the contact surface of the upper mold and the contact surface of the lower mold proximate the cavity at a vicinity of the cavity is about a thickness of the lead frame; and

wherein first air vents and second air vents that are independent from each other are formed in a lead frame to be pressed by the upper mold and the lower mold at the corners, and the first and second air vents are connected via the air releasing grooves.

3. (Currently Amended) The resin sealing mold assembly according to claim 2 , wherein the air releasing grooves are continuously formed from ~~said~~ the cavity and positioned almost over or under ~~said~~ the first air vent formed continuously from the cavity.

4. (Previously presented) The resin sealing mold assembly according to claim 2 , wherein the cavity formed by the upper mold and the lower mold includes a part of the first air vents.

5. (Currently Amended) The resin sealing mold assembly according to claim ~~1~~ 2 , wherein one end of each ~~said~~ air releasing groove positioned at the cavity side is formed at the contact surfaces distant from the cavity.

6. (Currently Amended) The resin sealing mold assembly according to claim 2, wherein the first air vents and the second air vents that are independent from each other are formed in the lead frame to be pressed by the upper mold and the lower mold at a plurality of corners, and a resin injection gate is formed at least at one of the corners, one end of the resin injection gate positioned at the cavity side is formed at the contact surfaces distant from the cavity, and the one end of the resin injection gate and the first air vent are continued to each other.

7. (Canceled)

8. (Currently Amended) The resin sealing mold assembly according to claim ~~1~~2, wherein ~~said~~the distance between the contact surface of the upper mold and the contact surface of the lower mold proximate the cavity at a vicinity of the cavity is essentially the same as a thickness of the lead frame.

U.S. Serial No. 10/772,345
Applicant: Isao OCHIAI

9. (Currently Amended) The resin sealing mold assembly according to claim ~~1~~2, wherein ~~said~~the lead frame is approximately 100 to 250 μ m.

10. Canceled.

11. (Currently Amended) The resin sealing mold assembly according to claim ~~1~~2, wherein ~~said~~ the distance between the contact surface of the upper mold and the contact surface of the lower mold proximate the cavity at a vicinity of the cavity is open by a degree corresponding to the thickness of the lead frame.

11. (Currently Amended) The resin sealing mold assembly according to claim 11, wherein ~~said~~ the vicinity of the cavity is adjacent ~~said~~ the cavity.